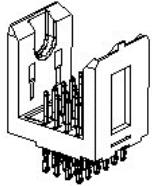



**Part Number: 85801-0124**

2.00mm Pitch MFB™ (Futurebus+) Header, Vertical, 4-Row or 5-Row, Press-Fit Pin, 69 Circuits, 4 Rows, First Mate / Last Break



Series Image - Reference only

<b>Status:</b>	<b>OBsolete</b>
<b>Replacement:</b>	Contact Molex
<b>Series:</b>	85801
<b>Category:</b>	Backplane Connectors

**Mates With Part(s):**
[54613](#), [54526](#), [54884](#), [54867](#), [54557](#), [54883](#)
**Product Environmental Compliance**
[EU RoHS](#): Compliance Status Not Reviewed

[China RoHS](#):

[REACH SVHC](#): Not Reviewed

[Low-Halogen Status](#): Not Reviewed

**Part Detail**
**General**

<b>Status</b>	<b>Obsolete</b>
Category	Backplane Connectors
Series	<a href="#">85801</a>
Application	Backplane
Comments	Backplane Header Module, Signal, Open
Component Type	PCB Header
Product Name	MFB™
Style	N/A

**Physical**

Circuits (Loaded)	69
Circuits (maximum)	96
Durability (mating cycles max)	250
First Mate / Last Break	Yes
Keying to Mating Part	Yes
Material - Plating Mating	Gold
Number of Columns	N/A
Number of Pairs	Open Pin Field
Number of Rows	4
Orientation	Vertical
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Polarized to PCB	Yes
Stackable	Yes
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +125°C

**Electrical**

(Please review the Product Specification for specific details.)

Current - Maximum per Contact	1A
Data Rate	622.0 Mbps
Voltage - Maximum	1000V

**Material Info**

UPC	800753294417
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**Reference - Drawing Numbers**

Product Specification	PS-85801-002
Sales Drawing	SD-85801-007, SD-85801-009

**Application Tooling**

Tooling specifications and manuals are found by selecting the products below.

Crimp Height Specifications are then contained in the Application Tooling

Specification document.

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**Previously Available Application**

**Tooling**

[Check our list of old tooling that used to be available for this part](#)